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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	172600
Number of Logic Elements/Cells	457000
Total RAM Bits	39936000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgsmd5k2f40c2n">https://www.e-xfl.com/product-detail/intel/5sgsmd5k2f40c2n</a>

**Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCD_FPLL</sub>	PLL digital power supply	−0.5	1.8	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	−0.5	3.4	V
V <sub>I</sub>	DC input voltage	−0.5	3.8	V
T <sub>J</sub>	Operating junction temperature	−55	125	°C
T <sub>STG</sub>	Storage temperature (No bias)	−65	150	°C
I <sub>OUT</sub>	DC output current per pin	−25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

**Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices**

Symbol	Description	Devices	Minimum	Maximum	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left side)	GX, GS, GT	−0.5	3.75	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right side)	GX, GS	−0.5	3.75	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	−0.5	3.75	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	−0.5	1.35	V
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	−0.5	1.35	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply (right side)	GT	−0.5	1.35	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	−0.5	1.8	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	−0.5	1.8	V

#### Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to −2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

**Table 5. Maximum Allowed Overshoot During Transitions**

Symbol	Description	Condition (V)	Overshoot Duration as % @ $T_J = 100^{\circ}\text{C}$	Unit
$V_i$ (AC)	AC input voltage	3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

**Figure 1. Stratix V Device Overshoot Duration**



**Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)**

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
$V_{CCR\_GXBR}$ (2)	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCR\_GTBR}$	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCT\_GXBL}$ (2)	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GXBR}$ (2)	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GTBR}$	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCL\_GTBR}$	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
$V_{CCH\_GXBL}$	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
$V_{CCH\_GXBR}$	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

**Notes to Table 7:**

- (1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.
- (2) Refer to Table 8 to select the correct power supply level for your design.
- (3) When using ATX PLLs, the supply must be 3.0 V.
- (4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

### I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

**Table 9. I/O Pin Leakage Current for Stratix V Devices <sup>(1)</sup>**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$

**Note to Table 9:**

(1) If  $V_O = V_{CCIO}$  to  $V_{CCIO\text{MAX}}$ , 100  $\mu\text{A}$  of leakage current per I/O is expected.

### Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

**Table 10. Bus Hold Parameters for Stratix V Devices**

Parameter	Symbol	Conditions	V <sub>CCIO</sub>										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
High sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (minimum)	−22.5	—	−25.0	—	−30.0	—	−50.0	—	−70.0	—	μA
Low overdrive current	I <sub>ODL</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	120	—	160	—	200	—	300	—	500	μA
High overdrive current	I <sub>ODH</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−120	—	−160	—	−200	—	−300	—	−500	μA
Bus-hold trip point	V <sub>TRIP</sub>	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

### On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices <sup>(1)</sup> (Part 1 of 2)**

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
25- $\Omega$ $R_S$	Internal series termination with calibration (25- $\Omega$ setting)	$V_{\text{CCIO}} = 3.0, 2.5, 1.8, 1.5, 1.2 \text{ V}$	$\pm 15$	$\pm 15$	$\pm 15$	$\pm 15$	%

**Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2, I2	C3, I3, I3YY	C4, I4	
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCPD</sub> = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

**Equation 1. OCT Variation Without Recalibration for Stratix V Devices <sup>(1), (2), (3), (4), (5), (6)</sup>**

$$R_{OCT} = R_{SCAL} \left( 1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

**Notes to Equation 1:**

- (1) The R<sub>OCT</sub> value shows the range of OCT resistance with the variation of temperature and V<sub>CCIO</sub>.
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V<sub>CCIO</sub> at power-up.
- (5) dR/dT is the percentage change of R<sub>SCAL</sub> with temperature.
- (6) dR/dV is the percentage change of R<sub>SCAL</sub> with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

**Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.0297	% / mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	

**Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices**

I/O Standard	$V_{CCIO}$ (V)			$V_{REF}$ (V)			$V_{TT}$ (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$V_{REF} - 0.04$	$V_{REF}$	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	$V_{REF}$	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
SSTL-12 Class I, II	1.14	1.20	1.26	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.53 * V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	—	—	—

**Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)**

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	$V_{OL}$ (V)	$V_{OH}$ (V)	$I_{OI}$ (mA)	$I_{OH}$ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	8	-8
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	16	-16
SSTL-135 Class I, II	—	$V_{REF} - 0.09$	$V_{REF} + 0.09$	—	$V_{REF} - 0.16$	$V_{REF} + 0.16$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-125 Class I, II	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-12 Class I, II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—

**Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)**

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	$V_{OL}$ (V)	$V_{OH}$ (V)	$I_{ol}$ (mA)	$I_{oh}$ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25^* V_{CCIO}$	$0.75^* V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25^* V_{CCIO}$	$0.75^* V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1^* V_{CCIO}$	$0.9^* V_{CCIO}$	—	—

**Table 20. Differential SSTL I/O Standards for Stratix V Devices**

I/O Standard	$V_{CCIO}$ (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.62	$V_{CCIO} + 0.6$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	$V_{CCIO} + 0.6$
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	$V_{CCIO}/2 - 0.15$	—	$V_{CCIO}/2 + 0.15$	0.35	—
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	—
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	—	$V_{REF} - 0.15$	$V_{CCIO}/2$	$V_{REF} + 0.15$	-0.30	0.30

**Note to Table 20:**

(1) The maximum value for  $V_{SWING(DC)}$  is not defined. However, each single-ended signal needs to be within the respective single-ended limits ( $V_{IH(DC)}$  and  $V_{IL(DC)}$ ).

**Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 1 of 2)**

I/O Standard	$V_{CCIO}$ (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—



Table 26 shows the approximate maximum data rate using the 10G PCS.

**Table 26. Stratix V 10G PCS Approximate Maximum Data Rate <sup>(1)</sup>**

Mode <sup>(2)</sup>	Transceiver Speed Grade	PMA Width	64	40	40	40	32	32
		PCS Width	64	66/67	50	40	64/66/67	32
FIFO or Register	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5
		C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88
	3	C1, C2, C2L, I2, I2L core speed grade	8.5 Gbps					
		C3, I3, I3L core speed grade						
		C4, I4 core speed grade						
		I3YY core speed grade	10.3125 Gbps					

**Notes to Table 26:**

- (1) The maximum data rate is in Gbps.
- (2) The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Table 27 shows the  $V_{OD}$  settings for the GX channel.

**Table 27. Typical  $V_{OD}$  Setting for GX Channel, TX Termination = 100  $\Omega$  <sup>(2)</sup>**

Symbol	$V_{OD}$ Setting	$V_{OD}$ Value (mV)	$V_{OD}$ Setting	$V_{OD}$ Value (mV)
<b><math>V_{OD}</math> differential peak to peak typical <sup>(3)</sup></b>	0 <sup>(1)</sup>	0	32	640
	1 <sup>(1)</sup>	20	33	660
	2 <sup>(1)</sup>	40	34	680
	3 <sup>(1)</sup>	60	35	700
	4 <sup>(1)</sup>	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
	15	300	47	940
	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

**Note to Table 27:**

- (1) If TX termination resistance = 100 $\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Reference Clock								
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL						
	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	—	40	—	710	40	—	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(6)</sup>	—	100	—	710	100	—	710	MHz
Rise time	20% to 80%	—	—	400	—	—	400	ps
Fall time	80% to 20%	—	—	400	—	—	400	
Duty cycle	—	45	—	55	45	—	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to −0.5	—	—	0 to −0.5	—	%
On-chip termination resistors <sup>(19)</sup>	—	—	100	—	—	100	—	Ω
Absolute V <sub>MAX</sub> <sup>(3)</sup>	Dedicated reference clock pin	—	—	1.6	—	—	1.6	V
	RX reference clock pin	—	—	1.2	—	—	1.2	
Absolute V <sub>MIN</sub>	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	mV
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin	1050/1000 <sup>(2)</sup>			1050/1000 <sup>(2)</sup>			mV
	RX reference clock pin	1.0/0.9/0.85 <sup>(22)</sup>			1.0/0.9/0.85 <sup>(22)</sup>			V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	mV

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
$t_{pll\_lock}$ <sup>(14)</sup>	—	—	—	10	—	—	10	μs

**Notes to Table 28:**

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR\_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9)  $t_{LTR}$  is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10)  $t_{LTD}$  is time required for the receiver CDR to start recovering valid data after the  $rx\_is\_lockedto\ data$  signal goes high.
- (11)  $t_{LTD\_manual}$  is the time required for the receiver CDR to start recovering valid data after the  $rx\_is\_lockedto\ data$  signal goes high when the CDR is functioning in the manual mode.
- (12)  $t_{LTR\_LTD\_manual}$  is the time the receiver CDR must be kept in lock to reference (LTR) mode after the  $rx\_is\_lockedto\ ref$  signal goes high when the CDR is functioning in the manual mode.
- (13)  $tp11\_powerdown$  is the PLL powerdown minimum pulse width.
- (14)  $tp11\_lock$  is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula:  
REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage  $V_{ID}$  after device configuration is equal to  $4 \times (\text{absolute } V_{MAX} \text{ for receiver pin} - V_{ICM})$ .
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR\_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Figure 4 shows the differential transmitter output waveform.

**Figure 4. Differential Transmitter/Receiver Output/Input Waveform**



Figure 5 shows the Stratix V AC gain curves for GT channels.

**Figure 5. AC Gain Curves for GT Channels**

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

**Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled**

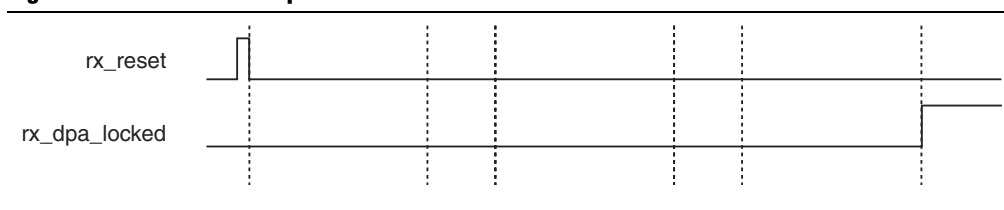


Table 37 lists the DPA lock time specifications for Stratix V devices.

**Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only <sup>(1), (2), (3)</sup>**

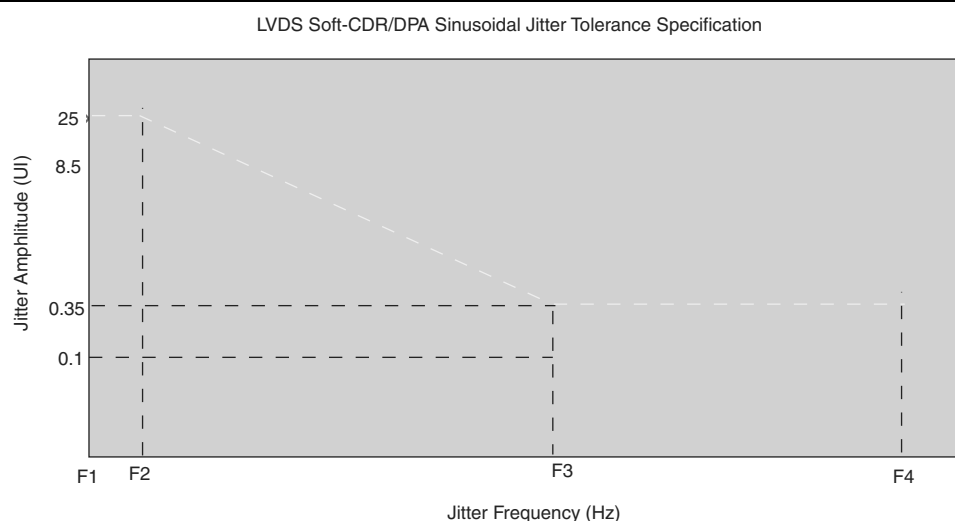
Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions <sup>(4)</sup>	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

**Notes to Table 37:**

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the LVDS soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps. Table 38 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps.

**Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $\geq 1.25$  Gbps**



**Table 42. Memory Output Clock Jitter Specification for Stratix V Devices <sup>(1)</sup>, (Part 2 of 2) <sup>(2)</sup>, <sup>(3)</sup>**

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
PHY Clock	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

**Notes to Table 42:**

- (1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.
- (2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.
- (3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

**OCT Calibration Block Specifications**

Table 43 lists the OCT calibration block specifications for Stratix V devices.

**Table 43. OCT Calibration Block Specifications for Stratix V Devices**

Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	—	—	20	MHz
$T_{OCTCAL}$	Number of OCTUSRCLK clock cycles required for OCT $R_S/R_T$ calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	—	Cycles
$T_{RS\_RT}$	Time required between the <code>dyn_term_ctrl</code> and <code>oe</code> signal transitions in a bidirectional I/O buffer to dynamically switch between OCT $R_S$ and $R_T$ (Figure 10)	—	2.5	—	ns

Figure 10 shows the timing diagram for the `oe` and `dyn_term_ctrl` signals.

**Figure 10. Timing Diagram for `oe` and `dyn_term_ctrl` Signals**

## Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

**Table 44. Worst-Case DCD on Stratix V I/O Pins <sup>(1)</sup>**

Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4, I4		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

**Note to Table 44:**

(1) The DCD numbers do not cover the core clock network.

## Configuration Specification

### POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

**Table 45. Fast and Standard POR Delay Specification <sup>(1)</sup>**

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

**Note to Table 45:**

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

### JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

**Table 46. JTAG Timing Parameters and Values for Stratix V Devices**

Symbol	Description	Min	Max	Unit
t <sub>JCP</sub>	TCK clock period <sup>(2)</sup>	30	—	ns
t <sub>JCP</sub>	TCK clock period <sup>(2)</sup>	167	—	ns
t <sub>JCH</sub>	TCK clock high time <sup>(2)</sup>	14	—	ns
t <sub>JCL</sub>	TCK clock low time <sup>(2)</sup>	14	—	ns
t <sub>JPSU (TDI)</sub>	TDI JTAG port setup time	2	—	ns
t <sub>JPSU (TMS)</sub>	TMS JTAG port setup time	3	—	ns



**Table 47. Uncompressed .rbf Sizes for Stratix V Devices**

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) <sup>(4), (5)</sup>
Stratix V E <sup>(1)</sup>	5SEE9	—	342,742,976	700,888
	5SEEB	—	342,742,976	700,888

**Notes to Table 47:**

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.tff) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.



For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices*. For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

**Table 48. Minimum Configuration Time Estimation for Stratix V Devices**

Variant	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel <sup>(2)</sup>		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GX	A3	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	B9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
	C7	4	100	0.675	32	100	0.084

**Table 49. DCLK-to-DATA[] Ratio <sup>(1)</sup> (Part 2 of 2)**

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

**Note to Table 49:**

- (1) Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

**Figure 11. Single Device FPP Configuration Using an External Host****Notes to Figure 11:**

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device.  $V_{CCPGM}$  must be high enough to meet the  $V_{IH}$  specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with  $V_{CCPGM}$ .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA[7..0]. If you use FPP ×16, use DATA[15..0].

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is 1.

**Table 50. FPP Timing Parameters for Stratix V Devices <sup>(1)</sup>**

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	—	600	ns
t <sub>CF2ST0</sub>	nCONFIG low to nSTATUS low	—	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	—	μs
t <sub>STATUS</sub>	nSTATUS low pulse width	268	1,506 <sup>(2)</sup>	μs
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	—	1,506 <sup>(3)</sup>	μs
t <sub>CF2CK</sub> <sup>(6)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	μs
t <sub>ST2CK</sub> <sup>(6)</sup>	nSTATUS high to first rising edge of DCLK	2	—	μs
t <sub>DSU</sub>	DATA [] setup time before rising edge on DCLK	5.5	—	ns
t <sub>DH</sub>	DATA [] hold time after rising edge on DCLK	0	—	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{\text{MAX}}$	—	s
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{\text{MAX}}$	—	s
t <sub>CLK</sub>	DCLK period	$1/f_{\text{MAX}}$	—	s
f <sub>MAX</sub>	DCLK frequency (FPP $\times 8/\times 16$ )	—	125	MHz
	DCLK frequency (FPP $\times 32$ )	—	100	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode <sup>(4)</sup>	175	437	μs
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(5)</sup>	—	—

**Notes to Table 50:**

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

### FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μs
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

**Notes to Table 53:**

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2)  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

**Figure 15. PS Configuration Timing Waveform <sup>(1)</sup>****Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Table 61. Document Revision History (Part 3 of 3)**

Date	Version	Changes
May 2013	2.7	<ul style="list-style-type: none"> <li>■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60</li> <li>■ Added Table 24, Table 48</li> <li>■ Updated Figure 9, Figure 10, Figure 11, Figure 12</li> </ul>
February 2013	2.6	<ul style="list-style-type: none"> <li>■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46</li> <li>■ Updated “Maximum Allowed Overshoot and Undershoot Voltage”</li> </ul>
December 2012	2.5	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35</li> <li>■ Added Table 33</li> <li>■ Added “Fast Passive Parallel Configuration Timing”</li> <li>■ Added “Active Serial Configuration Timing”</li> <li>■ Added “Passive Serial Configuration Timing”</li> <li>■ Added “Remote System Upgrades”</li> <li>■ Added “User Watchdog Internal Circuitry Timing Specification”</li> <li>■ Added “Initialization”</li> <li>■ Added “Raw Binary File Size”</li> </ul>
June 2012	2.4	<ul style="list-style-type: none"> <li>■ Added Figure 1, Figure 2, and Figure 3.</li> <li>■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.</li> <li>■ Various edits throughout to fix bugs.</li> <li>■ Changed title of document to <i>Stratix V Device Datasheet</i>.</li> <li>■ Removed document from the Stratix V handbook and made it a separate document.</li> </ul>
February 2012	2.3	<ul style="list-style-type: none"> <li>■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.</li> </ul>
December 2011	2.2	<ul style="list-style-type: none"> <li>■ Added Table 2–31.</li> <li>■ Updated Table 2–28 and Table 2–34.</li> </ul>
November 2011	2.1	<ul style="list-style-type: none"> <li>■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.</li> <li>■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.</li> <li>■ Various edits throughout to fix SPRs.</li> </ul>
May 2011	2.0	<ul style="list-style-type: none"> <li>■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.</li> <li>■ Updated the “DQ Logic Block and Memory Output Clock Jitter Specifications” title.</li> <li>■ Chapter moved to Volume 1.</li> <li>■ Minor text edits.</li> </ul>
December 2010	1.1	<ul style="list-style-type: none"> <li>■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.</li> <li>■ Converted chapter to the new template.</li> <li>■ Minor text edits.</li> </ul>
July 2010	1.0	Initial release.